

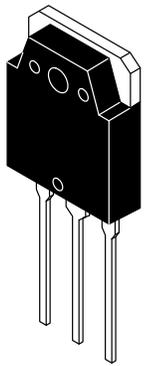
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

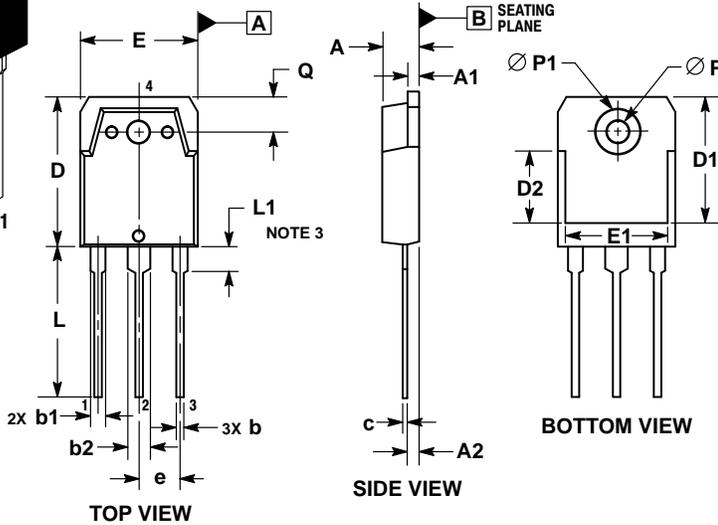


TO-3P-3L CASE 340AF ISSUE A

DATE 23 FEB 2016



SCALE 1:1

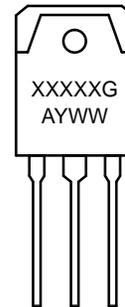


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. CONTOUR UNCONTROLLED IN THIS AREA.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH OR GATE PROTRUSIONS NOT TO EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE TO BE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
5. DIMENSIONS b1 AND b2 DO NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT EXCEED 0.10.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.60	4.80	5.00
A1	1.45	1.50	1.65
A2	1.20	1.40	1.60
b	0.80	1.00	1.20
b1	1.80	2.00	2.20
b2	2.80	3.00	3.20
c	0.55	0.60	0.75
D	19.70	19.90	20.10
D1	16.56	16.76	16.96
D2	9.80	10.00	10.20
E	15.40	15.60	15.80
E1	13.40	13.60	13.80
e	5.15	5.45	5.75
L	19.80	20.00	20.20
L1	3.30	3.50	3.70
P	3.00	3.20	3.40
P1	6.80	7.00	7.20
Q	4.80	5.00	5.20

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TO-3P-3L	PAGE 1 OF 2

